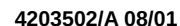


METAL SINGLE-IN-LINE MODULE



- NOTES:
- | | |
|--|---|
| A. All linear dimensions are in inches (mm). | H. The case is electrically uncommitted. The recommended connection is to the secondary ground plane. |
| B. This drawing is subject to change without notice. | I. Power pin connections should utilize two or more vias per input, ground and output pin. |
| C. 2 place decimals are ± 0.030 ($\pm 0,76\text{mm}$). | J. No copper power or signal traces in this area. |
| D. 3 place decimals are ± 0.010 ($\pm 0,25\text{mm}$). | K. Some pins may not be present, see product specifications. |
| E. Recommended mechanical keep out area. | |
| F. Vias are recommended to improve copper adhesion | |
| G. Solder mask openings to copper island for solder joints to mechanical pins. | |

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